



Title of Change:	Package Polyimide Tape Change
Effective date:	27 Nov 2019
Contact information:	Contact your local ON Semiconductor Sales Office or LengKian.See@onsemi.com
Type of notification:	This Product Bulletin is for notification purposes only. ON Semiconductor will proceed with implementation of this change upon publication of this Product Bulletin.
Change Category:	Assembly Change
Change Sub-Category(s):	Material Change

Sites Affected:

ON Semiconductor Sites	External Foundry/Subcon Sites
ON Semiconductor Cebu, Philippines	None

Description and Purpose:

This is to inform you that a change has been implemented in the products listed below.

Unless otherwise indicated in the details of this notification, the identified change will not impact form, fit, or function of the products. The affected products will remain fully compliant to all published specifications. Initial shipments lots, assembled with the type B polyimide tape were shipped from 11th July 2019 (Date Code: D1919), under special customers' arrangement. Full qualification testing was conducted in parallel with these shipments and the result published on 30th October is attached below:

Implementation of change:

Expected First Shipment Date for Changed Product After Full Qualification : Dec 6, 2019

Expected First Date Code of Changed Product After Full Qualification: D1945

Description of Change (From) :

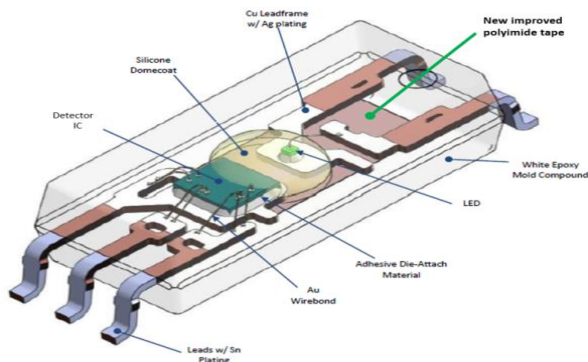
Type A polyimide tape within the package.

Description of Change (To) :

A new improved type B polyimide tape within the package.

Reason for Change:

The identified change will improve the reliability and robustness of the products.



This change will take immediate effect on the issue date of this notification. Please contact your local Customer Quality Engineer if you require any additional data or clarifications



SOIC-5 Optocoupler PI Tape Qualification

Test	#	Test Conditions	Reference	Comments	# Lots	S.S.	Results Fail/Total	Comments/ Test Results
Test Group A- Accelerated Environment Stress Tests								
PC	A1	Preconditioning: SMD only; Moist. Precond.	JESD22 A113 J-STD-020	Performed on surface mount devices prior to UHAST & TC	3	154	0/462	MSL- 1 @ 260°C
UHAST	A2	Unbiased Highly Accelerated Stress Test: 130°C/85% RH, ~ 18.8 psig, no bias for 96hrs.	JESD22 A118		3	77	0/231	
TC	A3	Temp Cycle: -40°C to +125°C; for 500 cycles	JESD22 A104		3	77	0/231	
HTSL	A4	High Temp Storage Life TA= 125°C for 1008 hrs	JESD22 A103		3	77	0/231	
Test Group B- Accelerated LifeTime Simulation Tests								
HTHV	B1	High Temp High Voltage: TA=125°C; Bias=1kV for 1008 hrs.	JESD22 A108		3	30	0/90	Aging test has successfully completed with no anomaly observed on the PI tape.
NOTES: Not recommended for Military, Medical or Aerospace Not for Automotive; Auto device may be available								

List of Affected Standard Parts:

Note: Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the [PCN Customized Portal](#).

FOD8321	FOD8321R2	FOD8321R2V
FOD8321V	FOD8383	FOD8383R2
FOD8383R2V	FOD8383V	FOD8384
FOD8384R2	FOD8384R2V	FOD8384V
FOD8320	FOD8160R2	FOD8160
FOD8320V	FOD8320R2V	FOD8320R2
FOD8160V	FOD8160R2V	